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HDP User Group Announces

Cave Creek, Arizona February 1, 2017. The High Density Packaging (HDP) User Group headquartered in the United States is pleased to announce the completion of its "Press Fit Technology Rework Project". This excellent Technical work also resulted in the HDP User Group team winning the best paper award at APEX Expo 2017.

More and more products use electronic devices to communicate. In 2020 it is expected that there will be more than 50 billion connected devices in the world. This means that many electronic products, especially mobile base stations and core network nodes, need to handle enormous amount of data per second. One important link in this communication chain are high speed press fit connectors that are often used to connect mother boards and back planes in core network nodes.

The goal with this project was to understand and to document how rework affects press fit connection strength, hole wall deformation and gas tight-ness for the newer high speed press fit connectors. Any weakness in these areas could lead to field failures.

The project was successful in evaluating five different high speed connector Types. The connectors were fine pitch, some with over 1000 pins fitting into plated through holes as small as 0.36 mm. The project quantified how many rework cycles could take place before damage occurred to the back plane.

The APEX award is very prestigious and recognizes the excellent technical work of the HDP User Group project team lead by Lars Bruno of Ericsson. Jack Fisher the project facilitator said *"This project, like most HDP projects was proposed by a member, confronting a problem that was important to their marketing success. The results of the project will significantly improve the quality of press fit containing products from all HDP User Group member companies."*

Please contact Jack Fisher at fish5er@hdpug.org for further information. The full technical report, containing all of the experimental data and conclusions is available to HDP User Group members.

About HDP User Group

HDP User Group (www.hdpug.org) is a global research and development



Technology Development in Today's Global Environment

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organization based in Cave Creek Arizona, is dedicated to "reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly". This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin, Texas, Singapore, and Dollar, U.K.

For more information, visit HDP User Group on the Internet at www.hdpug.org or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963